

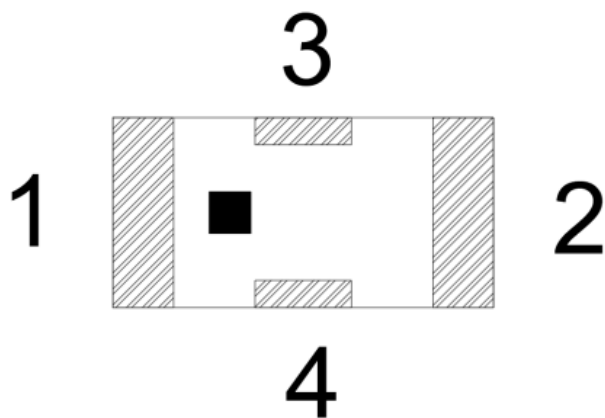
Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

Specifications

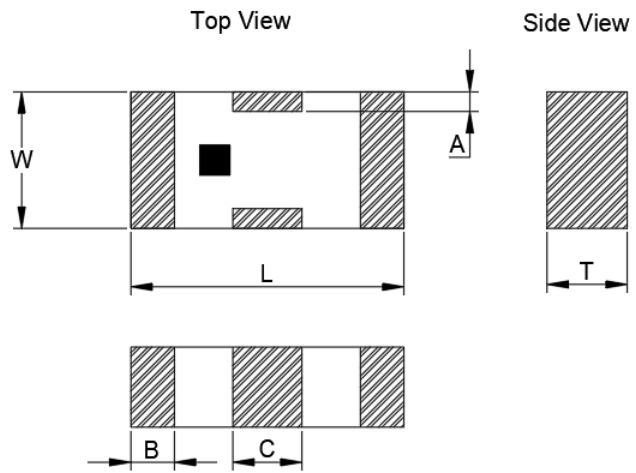
NO.	Parameter	Frequency (MHz)	SPC	
			Min.	Max.
1	Insertion Loss (dB)	2170~2380		3.0
2	VSWR	2170~2380		2.0
3	Attenuation (dB)	DC~1720	20	
		4200~6000	22	
4	In/Output Impedance (Ω)		50	

Construction

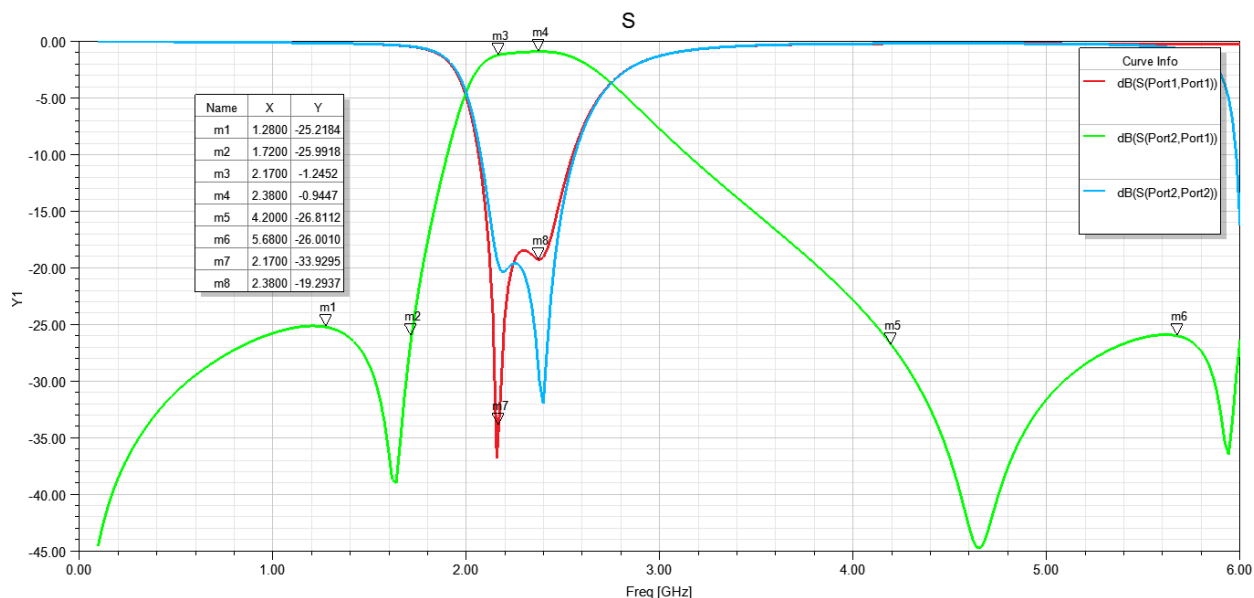


PIN	Connection
1	Input Port
2	Output Port
3	GND
4	GND

Dimensions

Figure	Symbol	Dimension (mm)
	L	3.20±0.10
	W	1.60±0.10
	T	0.94±0.10
	A	0.23±0.10
	B	0.51±0.10
	C	0.81±0.10

Typical Electrical Characteristics (T=25°C)



Solder Reflow Standard Conditioning



Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) *

Baking : Unnecessary

* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.